

TOSHIBA CORPORATION

Storage & Electronic Devices Solutions Company

3500, Matsuoka Oita City OITA 870-0197, JAPAN

PHONE: +81-97-524-6093

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Date: Sept. 20, 2016

Ref. No.: 0-HKN-16-00057B

To: Digi Key Corporation

Dear Sir/ Madam:

change of package assembly site and the wire material

We greatly appreciate your continued business.

This is to notify our customers of our plan to change wafer fab of our products supplied to you.

Full details of the planned change are given in the following page.

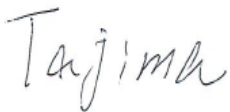
If you have any questions or inquiry regarding this change, please inform our Sales representatives nearest you as soon as possible.

We appreciate your understanding and cooperation.

Yours faithfully,

Reviewed by H. Kashima

Approved by I.Tajima, Manager



Quality Reliability Service Group

Oita Office

Quality & Reliability Engineering Dept.

Storage & Electronic Devices Solutions Company

TOSHIBA Corporation

change of package assembly site and the wire material

1. Product to be Affected : TC62D722CFNG(EL,H)
TC62D722CFNG(C,EL)
2. Description of Change : Change in assembly/testing/packing site and the wire material
3. Reason of Change : will be changed to Japan as part of consolidation of outsourcers
4. Scheduled Date of Change : We are planning to implement changeover from the beginning of August 2016 after customer approval period.
5. Remark : If you have any questions or requests regarding this change, please inform our Sales representatives nearest you as soon as possible.

Notice of Approval (For customer use)

Ref. No.: 0-HKN-16-00057B >

- We approve the above change.
- We approve the above change with the following conditions.
- We disapprove the above change for the following reasons.

[Specify the conditions/ reasons]

Date : _____

Company : _____

Department : _____

Approved by : _____